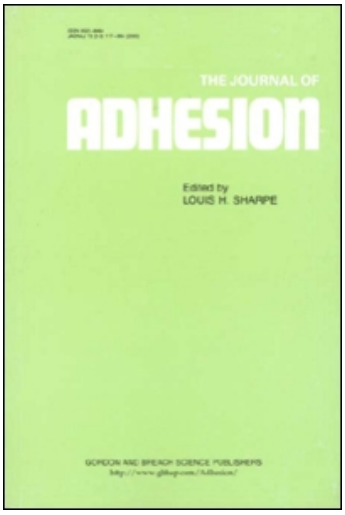


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# CALENDAR OF EVENTS

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## 2004

**June 28–30, 2004. Call for Papers—2nd New England International Nanomanufacturing Workshop: Breaking the Barriers to Nanomanufacturing to Enable the Commercialization of Nanotechnology, Northeastern University, Boston, MA.** Organized by Northeastern University, University of Massachusetts Lowell, and University of New Hampshire National Science Foundation.

Nanomanufacturing is expected to be high-volume, high-rate, integrated assembly of nano-elements into commercial products. This involves controlling position, orientation, and interconnectivity of the nano-elements. Increases in worldwide investments over the past few years have propelled nanoscience research scientific breakthrough to a new level. To ensure that these discoveries lead to commercially viable products, it is important to address fundamental scientific barriers to nanomanufacturing, in parallel with the ongoing nanoscience research. The goal of the workshop is to address moving from laboratory fabrication and prototyping into industry-floor manufacturing. The workshop will address the following:

1. Assembly of 3D heterogeneous systems: high volume manufacturing of three-dimensional systems, integration of manufacturing and assembly.
2. Reliability and yield issues: for nanoscale devices, reproducibility and repeatability of nanomanufacturing, control of nanoscale contamination, fault/defect tolerant devices.
3. Modeling: understanding of fundamental physics at the nanoscale, reliability models.
4. Nanomaterials: scale up production of nanomatertrials for manufacturing, cost.
5. Metrology: real-time characterization methods, monitoring, and characterization.
6. Infrastructure Issues: standards, instrumentation, tools, nanotechnology roadmap.

7. Cultural Issues: intellectual property issues, "nano-fear" in the public perception of nanotechnology.

Prospective authors are requested to submit an abstract of 200-300 words that includes a summary of significant results and a short biography by **Friday, April 30, 2004**. Please include the presenter's name, title, affiliation, address, telephone, fax, and e-mail. Authors selected to present at the symposium will be notified shortly after the above deadline. If your presentation is accepted, a copy of the presentation slides will be include in the workshop CD proceedings.

To submit an abstract for this Call for Papers, email your abstract to:

Angela Sutkaitis, Program Coordinator
Nanomanufacturing Research Institute
Tel.: (617) 373-3294, Fax: (617) 373-2921
E-mail: a.sutkaitis@neu.edu

For further information, please contact the Symposium Chair:
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E-mail: Busnaina@coe.neu.edu
For more information, visit http://www.nano.neu.edu/nanoworkshop2004/



**September 6–9, 2004 EURADH'04. The 7th European Adhesion Conference, EURADH'04, Freiburg in Breisgau, Germany.** In the tradition of former EURADH conferences, the organizers invite the international community of scientists, engineers, and practitioners to present their results on adhesion and related fields and to discuss new ideas and trends of development. The conference will be accompanied by a exhibition for products and equipment of interest for the science and technology of adhesion, surfaces, coatings and thin films.

Well-known scientists and representatives from industry have agreed to collaborate in the Scientific Committee: W. Possart (Conference Chair, Saarbrücken, GER), R. D. Adams (Bristol, UK), N. Blank (Zurich, SWISS), W. Brockmann (Kaiserslautern, GER), J. Cognard (Marin, SWISS), D. G. Dixon (Bristol, UK), S. Dieckhoff (Bremen, GER), F. Faupel (Kiel, GER), A. Hartwig (Bremen, GER), J.-J. Pireaux (Namur, BL), P. D. Poh (Frankfurt, GER), A. A. Roche (Villeurbanne, F), J. Schultz (Mulhouse, F), L. H. Sharpe (Williamsburg, VA, USA), C. Terfloth, (Detmold, GER), and W. Wittwer (Pirmasens, GER).

The topics of EURADH'04 will cover all aspects of adhesion and adhesives: recent advances in fundamental adhesion; surface chemis-

try; adhesion of biomolecules and bio-adhesion; modelling and simulation of interfaces and interphases; micromechanics and fracture mechanics of interphases, contact mechanics, and mechanics of adhesive joints; surface energetics; new chemistry for new adhesives; new hot melt, pressure sensitive and "green" adhesives; ageing mechanisms and durability; adhesion and tribology; advances in adhesion technologies and applications, including adhesion in microelectronics and technology, nanotechnology and adhesives, and adhesives in medicine; nondestructive evaluation of adhesive joints; and recycling and ecology. For further information or questions, please visit the Conference Website: http//www.euradh.org; E-mail: w.possart@mx.uni-saarland.de